



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	EBI/EMI, I ² C, LINbus, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	57
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	32K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b, 8x12b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f563tcddfp-v0

1. Overview

1.1 Outline of Specifications

Table 1.1 lists the specifications in outline, and Table 1.2 lists the functions of products.

Table 1.1 shows an outline of the maximum specifications, and the available peripheral modules and number of channels differ according to the number of pins on the package and the ROM capacity. For details, see Table 1.2, Comparison of Functions for Different Packages.

Table 1.1 Outline of Specifications (1/7)

Classification	Module/Function	Description
CPU	CPU	<ul style="list-style-type: none"> • Maximum operating frequency: 100 MHz • 32-bit RX CPU • Minimum instruction execution time: One instruction per state (cycle of the system clock) • Address space: 4-Gbyte linear • Register set of the CPU <ul style="list-style-type: none"> General purpose: Sixteen 32-bit registers Control: Nine 32-bit registers Accumulator: One 64-bit register • Basic instructions: 73 • Floating-point operation instructions: 8 • DSP instructions: 9 • Addressing modes: 10 • Data arrangement <ul style="list-style-type: none"> Instructions: Little endian Data: Selectable as little endian or big endian • On-chip 32-bit multiplier: $32 \times 32 \rightarrow 64$ bits • On-chip divider: $32 / 32 \rightarrow 32$ bits • Barrel shifter: 32 bits • Memory protection unit (MPU)
	FPU	<ul style="list-style-type: none"> • Single precision floating point (32 bits) • Data types and floating-point exceptions in conformance with the IEEE754 standard
Memory	ROM	<ul style="list-style-type: none"> • Capacity: 512 Kbytes, 384 Kbytes, 256 Kbytes, 64 Kbytes, 48 Kbytes, 32 Kbytes • 100 MHz, no-wait access • On-board programming: Programs can be modified through SCI or USB while the MCU is mounted on the board. • Off-board programming: Programs can be modified using parallel programmer. (only in 144-, 120-, 112- and 100-pin versions)
	RAM	<ul style="list-style-type: none"> • Capacity: 48 Kbytes, 32 Kbytes, 24 Kbytes, 8 Kbytes • 100 MHz, no-wait access
	E ² data flash	<ul style="list-style-type: none"> • Capacity: 32 Kbytes, 8 Kbytes • Programming/erasing: 100,000 times • On-board programming: <ul style="list-style-type: none"> Programs can be modified through SCI or USB while the MCU is mounted on the board. Programming from the user program is possible.
MCU operating modes		<p>[144-, 120-, 112- and 100-pin versions]</p> <p>Single-chip mode, on-chip ROM enabled extended mode, on-chip ROM disabled extended mode (switchable by software)</p> <p>[64- and 48-pin versions]</p> <p>Single-chip mode</p>

Table 1.4 Pin Functions (3/5)

Classifications	Pin Name	I/O	Description
Serial communications interface (SCIc)	Asynchronous mode/clock synchronous mode		
	SCK0, SCK1, SCK2, SCK3	I/O	Input/output pins for clock signals.
	RXD0, RXD1, RXD2, RXD3	Input	Input pins for data reception.
	TXD0, TXD1, TXD2, TXD3	Output	Output pins for data transmission.
	CTS0#, CTS1#, CTS2#, CTS3#	Input	Transmit/receive start control input pins
	RTS0#, RTS1#, RTS2#, RTS3#	Output	Transmit/receive start control output pins
	Simple I ² C mode		
	SSCL0, SSCL1, SSCL2, SSCL3	I/O	Input/output pins for the I ² C clock
	SSDA0, SSDA1, SSDA2, SSDA3	I/O	Input/output pins for the I ² C data
	Simple SPI mode		
	SCK0, SCK1, SCK2, SCK3	I/O	Input/output pins for the clock
	SMISO0, SMISO1, SMISO2, SMISO3	I/O	Input/output pins for slave transmit data.
	SMOSI0, SMOSI1, SMOSI2, SMOSI3	I/O	Input/output pins for master transmit data.
	SS0#, SS1#, SS2#, SS3#	Input	Input pins for chip select signals
Serial communications interface (SCId)	Asynchronous mode/clock synchronous mode		
	SCK12	I/O	Input/output pin for clock signals.
	RXD12	Input	Input pin for data reception.
	TXD12	Output	Output pin for data transmission.
	CTS12#	Input	Transmit/receive start control input pins
	RTS12#	Output	Transmit/receive start control output pins
	Simple I ² C mode		
	SSCL12	I/O	Input/output pins for the I ² C clock
	SSDA12	I/O	Input/output pins for the I ² C data
	Simple SPI mode		
	SCK12	I/O	Input/output pins for the clock
	SMISO12	I/O	Input/output pins for slave transmit data.
I ² C bus interface	SMOSI12	I/O	Input/output pins for master transmit data.
	SS12#	Input	Input pins for chip select signals
Extended serial mode	Extended serial mode		
	RDX12	Input	Input pin for receive data
	TXDX12	Output	Output pin for transmit data
	SIOX12	I/O	Input/output pin for transfer data
I ² C bus interface	SCL, SCL0, SCL1	I/O	Clock input/output pin. N-channel open drain can directly drive buses.
	SDA, SDA0, SDA1	I/O	Data input/output pin. N-channel open drain can directly drive buses.

Table 1.10 List of Pins and Pin Functions (48-Pin LQFP) (2/2)

Pin Number 64-Pin LQFP	Power Supply Clock System Control	I/O Port	POE3	Timer (MTU3, GPT, CAC)	Communications		Interrupt	S12ADB
					(SCIc, SCId)	(RSPI, RIIC)		
26		P74		MTIOC3D GTIOC0B MTIOC6D				
27		P73		MTIOC4B GTIOC2A MTIOC7B				
28		P72		MTIOC4A GTIOC1A MTIOC7A				
29		P71		MTIOC3B GTIOC0A MTIOC6B				
30		P70	POE0#		CTS1# RTS1# SS1#		IRQ5-DS	
31	VCC							
32		P30		MTIOC0B MTCLKD	TXD0 SMOSI0 SSDA0	SSLA0		
33	VSS							
34		P24		MTIC5U MTCLKC	RXD0 SMISO0 SSCLO	RSPCKA		
35		P23		MTIC5V MTCLKB CACREF	SCK0	MOSIA		
36		P22		MTIC5W MTCLKA	CTS0# RTS0# SS0#	MISOA		
37		P47						AN007 CVREFH
38		P44						AN004
39		P43						AN003 CVREFL
40		P42						AN002
41		P41						AN001
42		P40						AN000
43	AVCC0							
44	VREFH0							
45	VREFL0							
46	AVSS0							
47	VCL							
48	EMLE							

2. CPU

The RX CPU has sixteen general-purpose registers, nine control registers, and one accumulator used for DSP instructions.

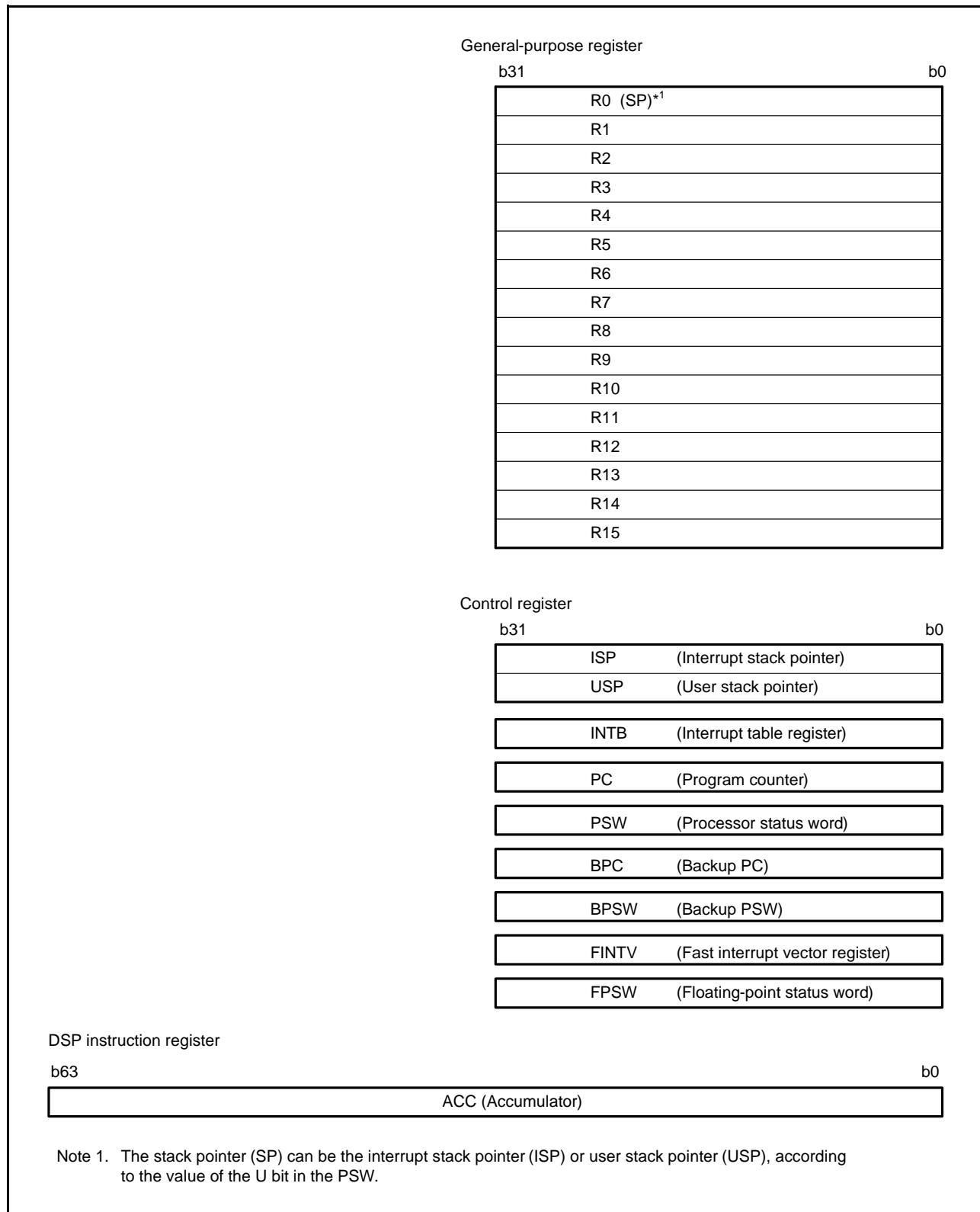


Figure 2.1 Register Set of the CPU

5. Electrical Characteristics [144-, 120-, 112- and 100-Pin Versions]

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Conditions: VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V

Item	Symbol	Value	Unit
Power supply voltage	VCC, PLLVCC	-0.3 to +6.5	V
USB power supply voltage	VCC_USB ^{*1}	-0.3 to +6.5	V
Analog power supply voltage	AVCC0, AVCC ^{*2}	-0.3 to +6.5	V
Reference power supply voltage	VREFH0 ^{*2}	-0.3 to AVCC0 + 0.3	V
	VREF ^{*2}	-0.3 to AVCC0 + 0.3	V
Input voltage (except for ports 4 to 6, C, USB0_DP, and USB0_DM)	V _{in}	-0.3 to VCC + 0.3	V
Input voltage (USB0_DP and USB0_DM)	V _{in}	-0.3 to VCC_USB + 0.3	V
Input voltage (port 4)	V _{in}	-0.3 to AVCC0 + 0.3	V
Input voltage (ports 5, 6, and C)	V _{in}	-0.3 to AVCC + 0.3	V
Analog input voltage (port 4)	V _{AN}	-0.3 to AVCC0 + 0.3	V
Analog input voltage (ports 5, 6, and C)	V _{AN}	-0.3 to AVCC + 0.3	V
Operating temperature	D version product	T _{opr}	°C
	G version product	T _{opr}	°C
Storage temperature	T _{stg}	-55 to +125	°C

Caution: Permanent damage to the LSI may result if absolute maximum ratings are exceeded.

Note 1. When the USB is not in use, do not leave the VCC_USB and VSS_USB pins open.

Connect the VCC_USB pin to VCC, and the VSS_USB pin to VSS, respectively.

Note 2. When the A/D converter is not in use, do not leave the AVCC0, VREFH0, VREFL0, AVSS0, AVCC, VREF, and AVSS pins open.

- When the 12-bit A/D converter is not in use

Connect the AVCC0 pin to AVCC, the VREFH0 pin to VREF, and the AVSS0 and VREFL0 pins to AVSS, respectively.

- When the 10-bit A/D converter is not in use

Connect the AVCC pin to AVCC0, the VREF pin to VREFH0, and the AVSS pin to AVSS0, respectively.

- When the 12-bit A/D converter and 10-bit A/D converter are not in use

Connect the AVCC0, VREFH0, AVCC, and VREF pins to VCC, and the AVSS0, VREFL0, and AVSS pins to VSS, respectively.

5.3.5 Bus Timing

Table 5.12 Bus Timing (1)

Condition: VCC = PLLVCC = VCC_USB = AVCC0 = AVCC = 3.0 to 3.6 V,

VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V

VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

 $T_a = T_{opr}$ Output load conditions: $V_{OH} = VCC \times 0.5$, $V_{OL} = VCC \times 0.5$, $I_{OH} = -1.0 \text{ mA}$, $I_{OL} = 1.0 \text{ mA}$, $C = 30 \text{ pF}$

Item	Symbol	Min.	Max.	Unit	Test Conditions
Address delay time	t_{AD}	—	30	ns	Figure 5.13 to Figure 5.16
Byte control delay time	t_{BCD}	—	30	ns	
CS# delay time	t_{CSD}	—	30	ns	
RD# delay time	t_{RSD}	—	30	ns	
Read data setup time	t_{RDS}	20	—	ns	
Read data hold time	t_{RDH}	0	—	ns	
WR# delay time	t_{WRD}	—	30	ns	
Write data delay time	t_{WDD}	—	35	ns	
Write data hold time	t_{WDH}	0	—	ns	
WAIT# setup time	t_{WTS}	20	—	ns	Figure 5.17
WAIT# hold time	t_{WTH}	0	—	ns	

Table 5.13 Bus Timing (2)

Condition: VCC = PLLVCC = AVCC0 = AVCC = 4.0 to 5.5 V, VCC_USB = 3.0 to 3.6 V,

VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V

VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

 $T_a = T_{opr}$ Output load conditions: $V_{OH} = VCC \times 0.5$, $V_{OL} = VCC \times 0.5$, $I_{OH} = -1.0 \text{ mA}$, $I_{OL} = 1.0 \text{ mA}$, $C = 30 \text{ pF}$

Item	Symbol	Min.	Max.	Unit	Test Conditions
Address delay time	t_{AD}	—	15	ns	Figure 5.13 to Figure 5.16
Byte control delay time	t_{BCD}	—	15	ns	
CS# delay time	t_{CSD}	—	15	ns	
RD# delay time	t_{RSD}	—	15	ns	
Read data setup time	t_{RDS}	15	—	ns	
Read data hold time	t_{RDH}	0	—	ns	
WR# delay time	t_{WRD}	—	15	ns	
Write data delay time	t_{WDD}	—	15	ns	
Write data hold time	t_{WDH}	0	—	ns	
WAIT# setup time	t_{WTS}	15	—	ns	Figure 5.17
WAIT# hold time	t_{WTH}	0	—	ns	

Table 5.16 Timing of On-Chip Peripheral Modules (4)

Note: Common standard values for conditions not given in the table are listed as "Condition 1" to "Condition 3" below.

Condition 1: VCC = PLLVCC = VCC_USB = 2.7 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0

Condition 2: VCC = PLLVCC = VCC_USB = 2.7 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VCC_USB = 3.0 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0

$T_a = T_{opr}$. T_a is common to conditions 1 to 3.

Item	Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)	t_{SPcyc}	4	65536	$C = 30 \text{ pF}$, Figure 5.30
	SCK clock cycle input (slave)		8	65536	
	SCK clock high pulse width	t_{SPCKWH}	0.4	0.6	
	SCK clock low pulse width	t_{SPCKWL}	0.4	0.6	
	SCK clock rise/fall time	t_{SPCKR}, t_{SPCKF}	—	20	
	Data input setup time	t_{SU}	40	—	
	Data input hold time	t_H	40	—	
	SS input setup time	t_{LEAD}	6	—	
	SS input hold time	t_{LAG}	6	—	
	Data output delay time	t_{OD}	—	40	
	Data output hold time	t_{OH}	-10	—	
	Data rise/fall time	t_{DR}, t_{DF}	—	20	
	SS input rise/fall time	t_{SSLr}, t_{SSLf}	—	20	
	Slave access time	t_{SA}	—	5	$C = 30 \text{ pF}$, Figure 5.37 and Figure 5.38
	Slave output release time	t_{REL}	—	5	t_{Pcyc}

Note 1. t_{Pcyc} : PCLK cycle

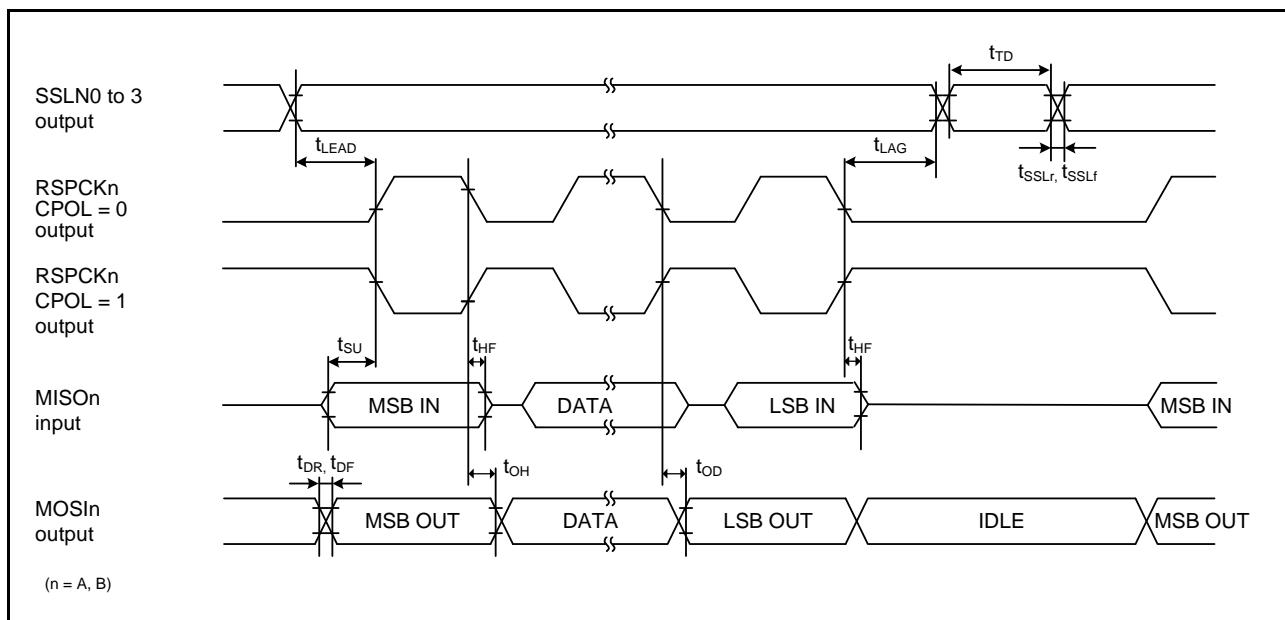


Figure 5.31 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Division Ratio Set to 1/2)

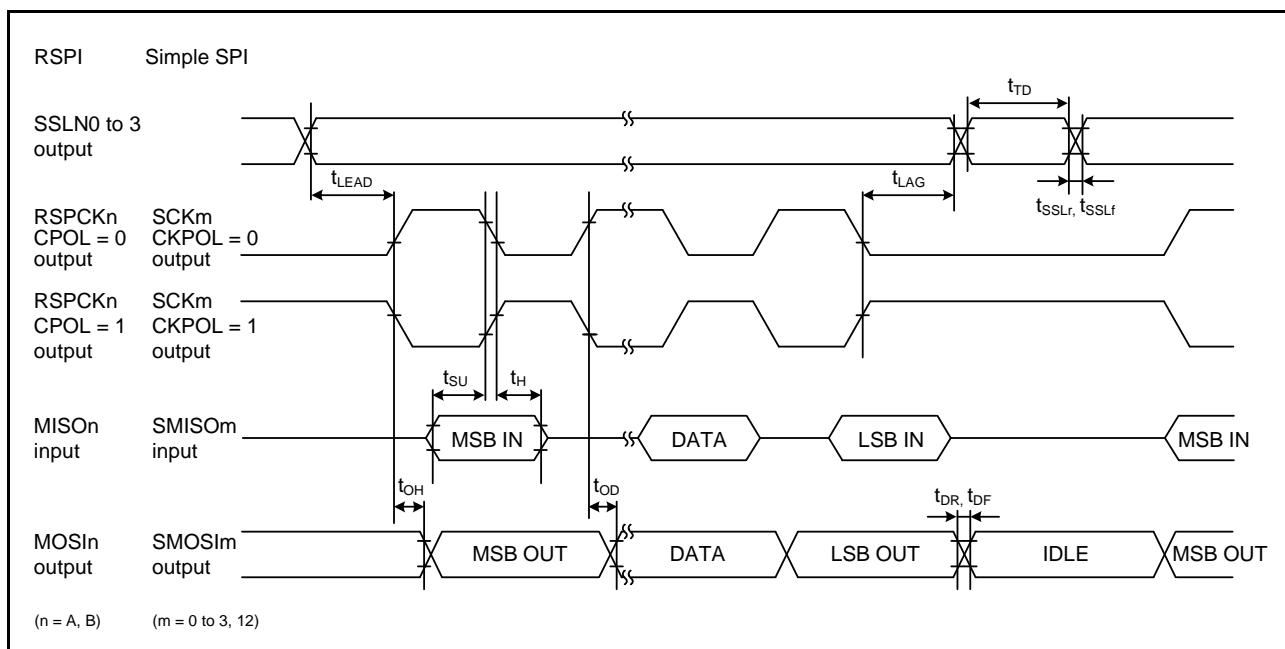


Figure 5.32 RSPI Timing (Master, CPHA = 1) (Bit Rate: PCLKB Division Ratio Set to a Value Other Than 1/2) and Simple SPI Timing (Master, CKPH = 0)

5.5 A/D Conversion Characteristics

Table 5.19 10-Bit A/D Conversion Characteristics (1)

Note: Common standard values for conditions not given in the table are listed as "Condition 1" to "Condition 3" below.

Condition 1: VCC = PLLVCC = VCC_USB = 2.7 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0

Condition 2: VCC = PLLVCC = VCC_USB = 2.7 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VCC_USB = 3.0 to 3.6 V, VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = VREF = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0

T_a = T_{opr}. T_a is common to conditions 1 to 3.

Item		Min.	Typ.	Max.	Unit	Test Conditions	
Resolution		10	10	10	Bit		
Conversion time*1 (Operation at ADCLK = 100 MHz)	With 0.1- μ F external capaci- tor	AN0 to AN7	0.5	—	—	μ s Sampling in 25 states	
		Other channels	0.75	—	—	μ s Sampling in 50 states	
	Without 0.1- μ F external capaci- tor Permissible sig- nal source impedance (max.) = 1 k Ω	AN0 to AN7	0.6	—	—	μ s Sampling in 35 states	
		Other channels	0.75	—	—	μ s Sampling in 50 states	
Analog input capacitance		—	—	6	pF		
Integral nonlinearity error		—	—	\pm 3.0	LSB		
Offset error		—	—	\pm 2.0	LSB		
Full-scale error		—	—	\pm 3.0	LSB		
Quantization error		—	\pm 0.5	—	LSB		
Absolute accuracy		—	—	\pm 6.0	LSB		

Note 1. The conversion time includes the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

5.7 Power-on Reset Circuit and Voltage Detection Circuit Characteristics

Table 5.26 Power-on Reset Circuit and Voltage Detection Circuit Characteristics (1)

Note: Common standard values for conditions not given in the table are listed as "Condition 1" and "Condition 2" below.

Condition 1: $VCC = PLLVCC = VCC_USB = 2.7$ to 3.6 V, $VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0$ V
 $AVCC0 = AVCC = VREF = 3.0$ to 3.6 V, $VREFH0 = 3.0$ V to $AVCC0$

Condition 2: $VCC = PLLVCC = VCC_USB = 2.7$ to 3.6 V, $VSS = PLLVSS = VSS_USB = AVSS0 = AVSS = VREFL0 = 0$ V
 $AVCC0 = AVCC = VREF = 4.0$ to 5.5 V, $VREFH0 = 4.0$ V to $AVCC0$

$T_a = T_{opr}$. T_a is common to conditions 1 and 2.

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Voltage detection level	V_{POR}	2.46	2.58	2.7	V	Figure 5.41
	V_{DET0}	2.7	2.82	2.94		Figure 5.42
	V_{DET1_8}	2.75	2.90	3.05		Figure 5.43
	V_{DET1_9}	2.70	2.85	3.00		
	V_{DET1_A}	2.73	2.88	3.03		
	V_{DET2_8}	2.75	2.9	3.05		Figure 5.44
Internal reset time	V_{DET2_9}	2.70	2.85	3.00	ms	Figure 5.41
	V_{DET2_A}	2.73	2.88	3.03		Figure 5.42
	t_{POR}		9.7			Figure 5.43
	t_{LVDO}		9.7			Figure 5.44
Minimum VCC down time*3	t_{VOFF}	200	—	—	μs	Figure 5.41 and Figure 5.42
Response delay time	t_{DET}			200	μs	
LVD operation stabilization time (after LVD is enabled)	$Td(E-A)$			3	μs	Figure 5.41 to Figure 5.44
Hysteresis width (LVD1 and LVD2)	V_{LVH}		80		mV	

Note 1. # in symbol $V_{DET1_#}$ indicates the value of the LVLDLVR.LVD1LVL[3:0] bits.

Note 2. # in symbol $V_{DET2_#}$ indicates the value of the LVLDLVR.LVD2LVL[3:0] bits.

Note 3. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR} , V_{DET1} , and V_{DET2} for the POR/LVD.

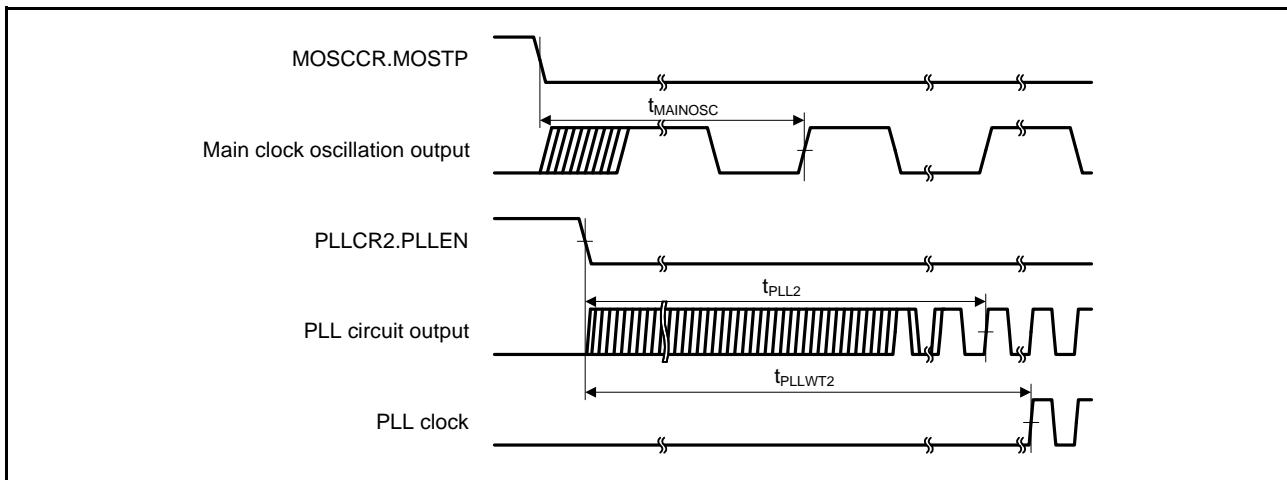


Figure 6.5 PLL Clock Oscillation Start Timing (PLL is Operated before Main Clock Oscillation Has Settled)

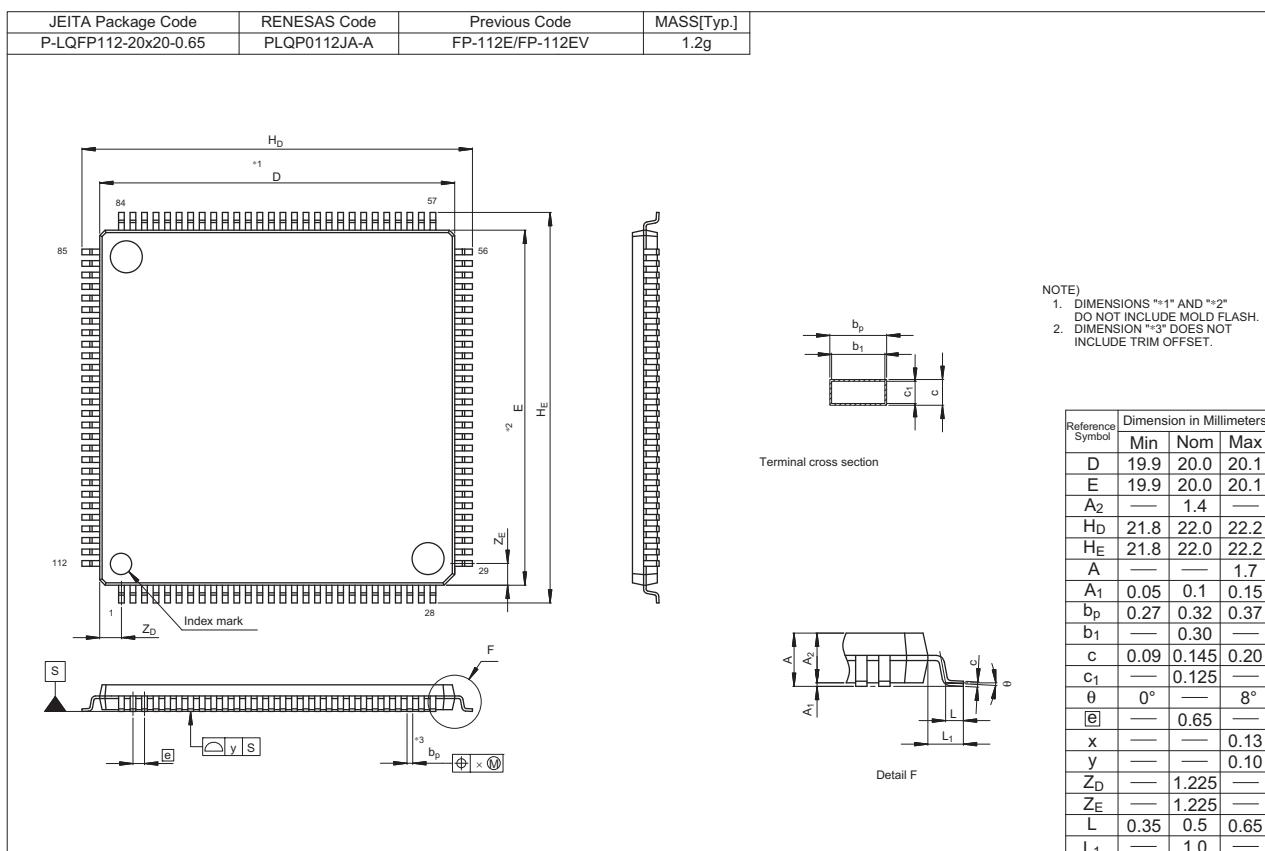


Figure C 112-Pin LQFP (PLQP0112JA-A)

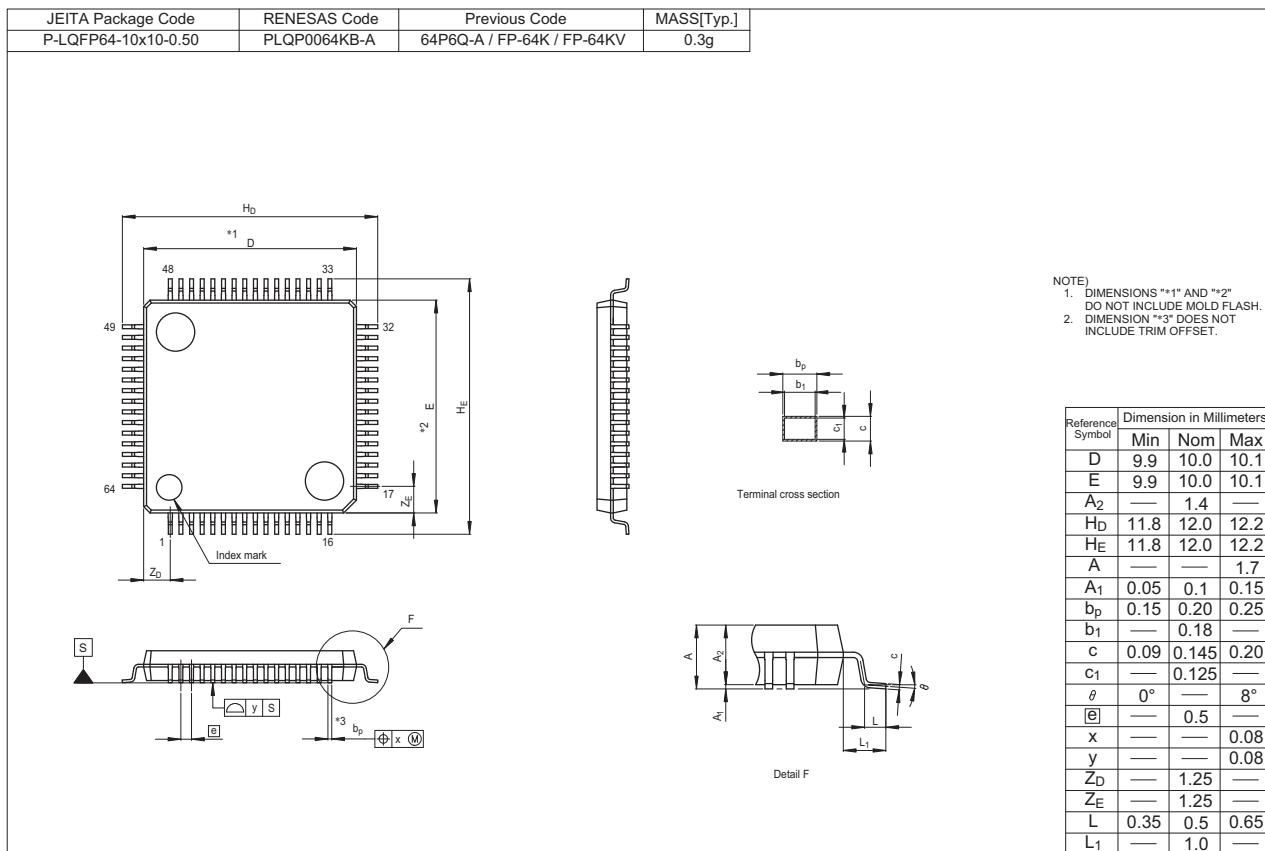


Figure E 64-Pin LQFP (PLQP0064KB-A)